

A

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REV	DESCRIPTION	DESIGN	DATE
A0	Release	吴丹平	2016.04.30

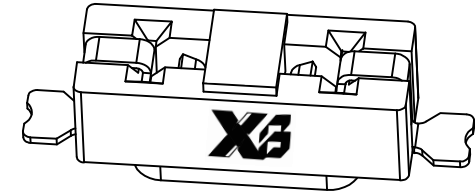
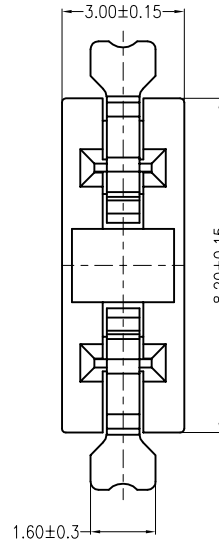
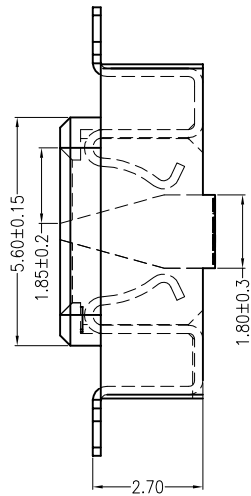
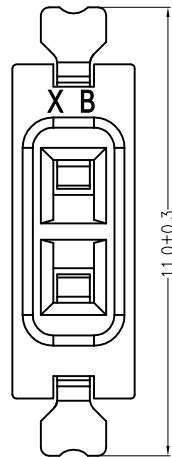
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主要技术参数 Main Specifications

线 数 (Poles): 02

接触电阻 (Contact resistance): $\leq 20\text{m}\Omega$

绝缘电阻 (Insulation resistance): $\geq 1000\text{M}\Omega$

额定电压 (Rated voltage): 125V AC DC

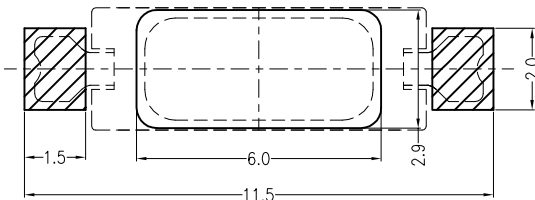
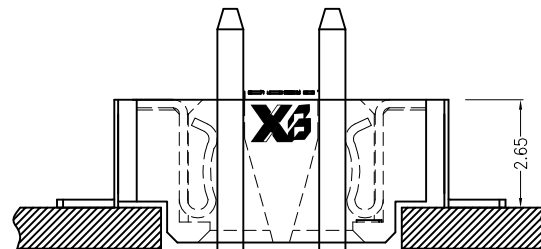
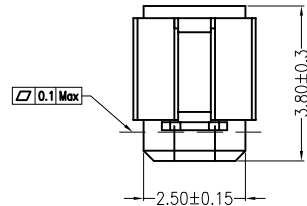
额定电流 (Rated current): 1.0A AC DC

耐 电 压 (Withstand Voltage): 1500V AC/minute

温度范围 (Temperature Range): $-40^{\circ}\text{C} \sim +120^{\circ}\text{C}$

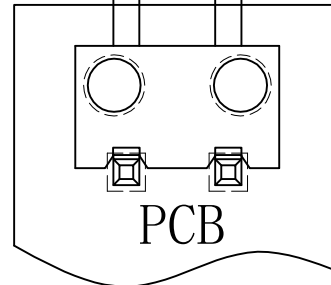
ORDER INFORMATION:

XB-L039Y-02-F2MB-R			
PART No.			PACKAGING:
No. FOR CIRCUITS:			P=PE
02			R=REEL
PLASTIC MATERIAL:			PLATING:
F2M=LCP (BEIGE)			B=MATTE Sn



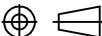
Board Layout

General Tolerance: ± 0.05



PCB

Assembly Layout

C					
B	CONTACT		2 PCS	PhosphorBronze	MATTE Sn-plated
A	PEDESTAL		1 PCS	LCP	UL 94V-0, COLOR:BEIGE
ITEM	COMPONENT		Q'TY	MATERIAL	FINISH
 东莞市溪榜电子有限公司 DONG GUAN XI BANG ELECTRONICS CO.,LTD TITLE: - 2.5mmPITCH 180°WAFER SMT TYPE					
X.±0.5	X.±5°	USE: CUSTOMER	PART NO.:		
.X±0.3	.X±2°		L039Y-02-F2MB-R		
.XX±0.25	.XX±1°		DWG NO.:		
--	--		GCCP-0065		
	UNITS: mm	DR:	SCALE		SHEET 1 / 1
		吴丹平	1 : 1		